

General Description

The GreenMOS® high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

The GreenMOS® Generic series is optimized for extreme switching performance to minimize switching loss. It is tailored for high power density applications to meet the highest efficiency standards.

Features

- Low $R_{DS(on)}$ & FOM
- Extremely low switching loss
- Excellent stability and uniformity



Applications

- PC power
- LED lighting
- Telecom power
- Server power
- EV Charger
- Solar/UPS

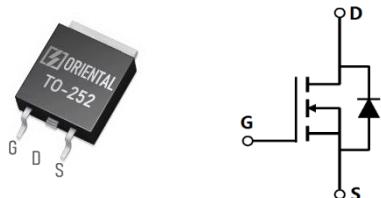
Key Performance Parameters

Parameter	Value	Unit
$V_{DS, min} @ T_{j(max)}$	650	V
$I_D, pulse$	21	A
$R_{DS(ON), max} @ V_{GS}=10V$	670	mΩ
Q_g	7.8	nC

Marking Information

Product Name	Package	Marking
OSG60R670DF	TO252	OSG60R670D

Package & Pin Information



Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	V_{DS}	600	V
Gate-source voltage	V_{GS}	± 30	V
Continuous drain current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$	I_D	7	A
Continuous drain current ¹⁾ , $T_C=100\text{ }^\circ\text{C}$		4.4	
Pulsed drain current ²⁾ , $T_C=25\text{ }^\circ\text{C}$	$I_{D,\text{pulse}}$	21	A
Continuous diode forward current ¹⁾ , $T_C=25\text{ }^\circ\text{C}$	I_S	7	A
Diode pulsed current ²⁾ , $T_C=25\text{ }^\circ\text{C}$	$I_{S,\text{pulse}}$	21	A
Power dissipation ³⁾ , $T_C=25\text{ }^\circ\text{C}$	P_D	37	W
Single pulsed avalanche energy ⁵⁾	E_{AS}	130	mJ
MOSFET dv/dt ruggedness, $V_{DS}=0\text{...}480\text{ V}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}=0\text{...}480\text{ V}$, $I_{SD}\leq I_D$	dv/dt	15	V/ns
Operation and storage temperature	T_{stg}, T_j	-55 to 150	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	$R_{\theta JC}$	3.4	$^\circ\text{C/W}$
Thermal resistance, junction-ambient ⁴⁾	$R_{\theta JA}$	62	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	BV_{DSS}	600			V	$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$
		650	750			$V_{GS}=0\text{ V}$, $I_D=250\text{ }\mu\text{A}$, $T_j=150\text{ }^\circ\text{C}$
Gate threshold voltage	$V_{GS(\text{th})}$	2.0		4.0	V	$V_{DS}=V_{GS}$, $I_D=250\text{ }\mu\text{A}$
Drain-source on-state resistance	$R_{DS(\text{ON})}$		0.6	0.67	Ω	$V_{GS}=10\text{ V}$, $I_D=3.5\text{ A}$
			1.38			$V_{GS}=10\text{ V}$, $I_D=3.5\text{ A}$, $T_j=150\text{ }^\circ\text{C}$
Gate-source leakage current	I_{GSS}			100	nA	$V_{GS}=30\text{ V}$
				-100		$V_{GS}=-30\text{ V}$
Drain-source leakage current	I_{DSS}			1	μA	$V_{DS}=600\text{ V}$, $V_{GS}=0\text{ V}$

Dynamic Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	C _{iss}		353		pF	V _{GS} =0 V, V _{DS} =50 V, f=1 MHz
Output capacitance	C _{oss}		46.9		pF	
Reverse transfer capacitance	C _{rss}		1.9		pF	
Turn-on delay time	t _{d(on)}		16.9		ns	V _{GS} =10 V, V _{DS} =400 V, R _G =25 Ω, I _D =3 A
Rise time	t _r		7.1		ns	
Turn-off delay time	t _{d(off)}		32.9		ns	
Fall time	t _f		26.2		ns	

Gate Charge Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Total gate charge	Q _g		7.8		nC	V _{GS} =10 V, V _{DS} =400 V, I _D =3 A
Gate-source charge	Q _{gs}		2		nC	
Gate-drain charge	Q _{gd}		3.3		nC	
Gate plateau voltage	V _{plateau}		5.6		V	

Body Diode Characteristics

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Diode forward voltage	V _{SD}			1.3	V	I _S =7 A, V _{GS} =0 V
Reverse recovery time	t _{rr}		172		ns	V _R =400 V, I _S =3 A, di/dt=100 A/μs
Reverse recovery charge	Q _{rr}		1.5		μC	
Peak reverse recovery current	I _{rrm}		12.8		A	

Note

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{θJA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, V_{GS}=10 V, L=20 mH, starting T_j=25 °C.

Electrical Characteristics Diagrams

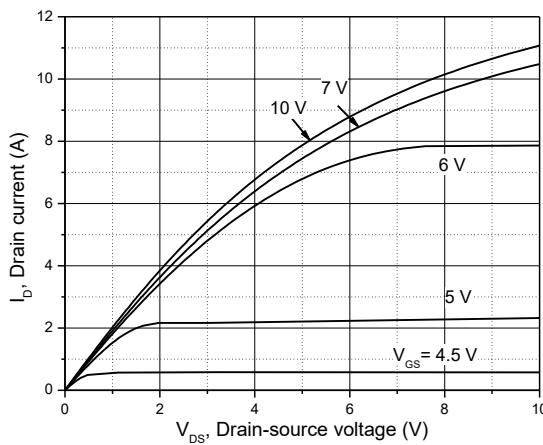


Figure 1. Typ. output characteristics

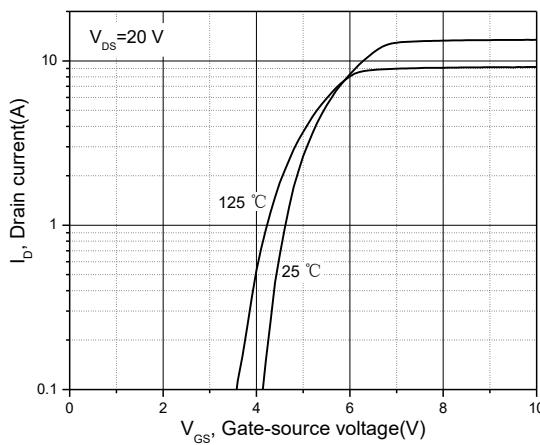


Figure 2. Typ. transfer characteristics

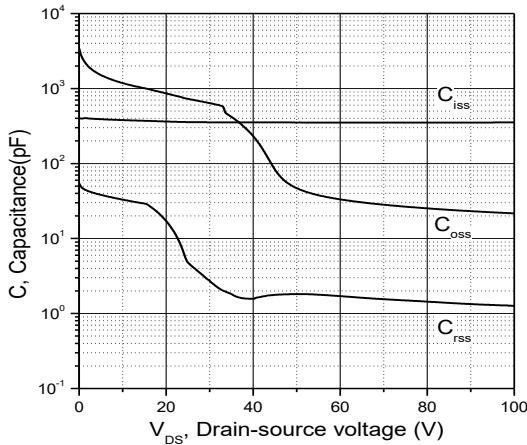


Figure 3. Typ. capacitances

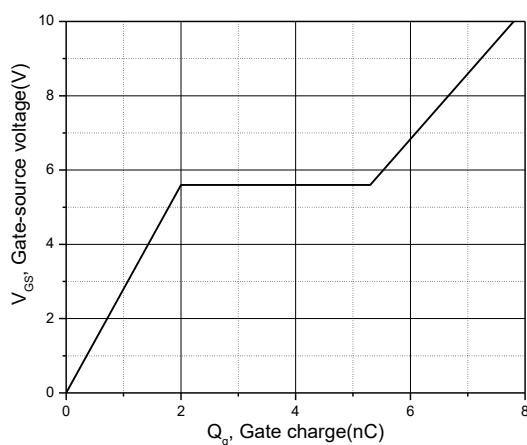


Figure 4. Typ. gate charge

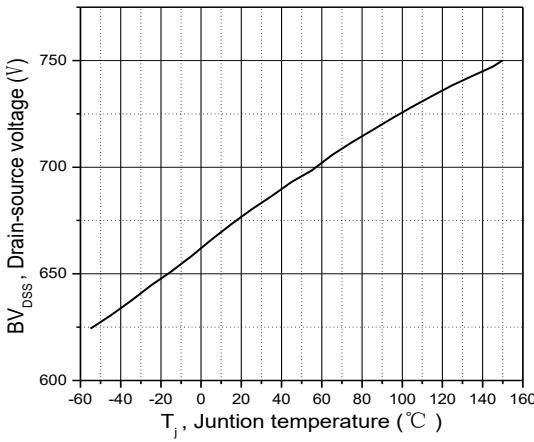


Figure 5. Drain-source breakdown voltage

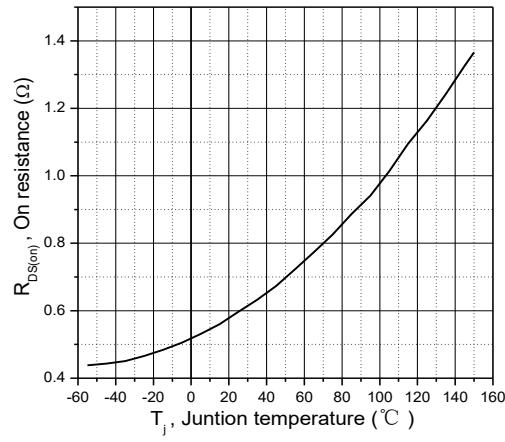


Figure 6. Drain-source on-state resistance

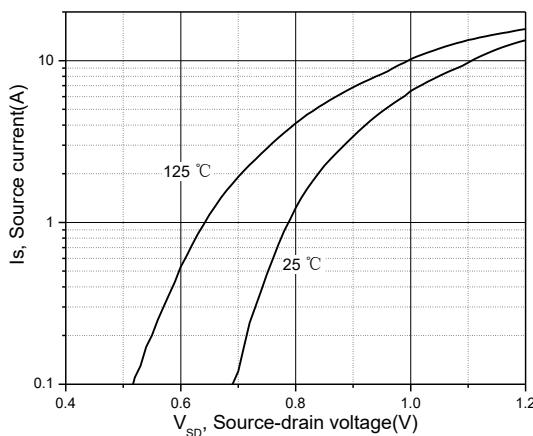


Figure 7. Forward characteristic of body diode

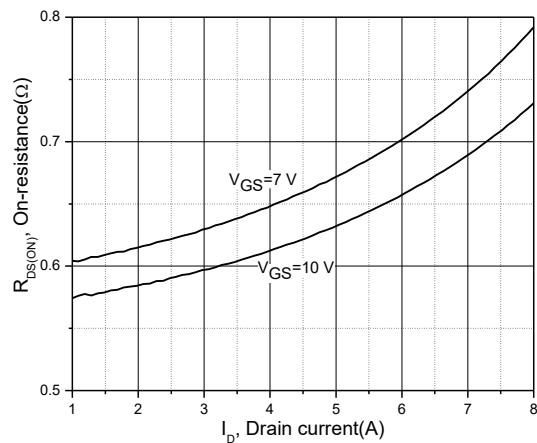


Figure 8. Drain-source on-state resistance

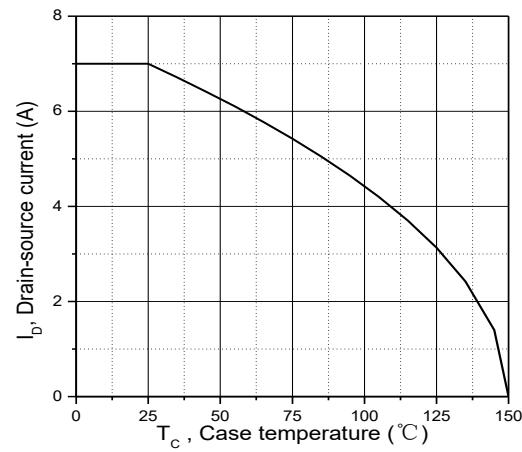


Figure 9. Drain current

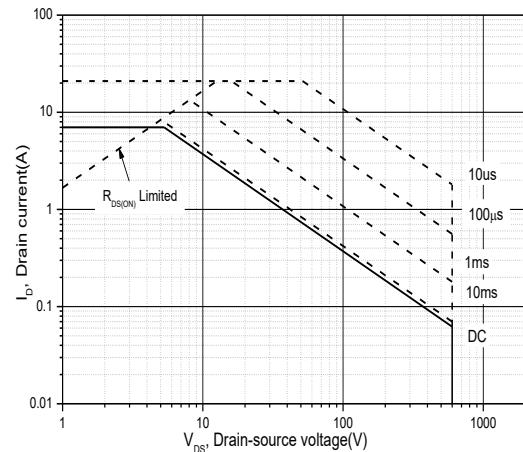
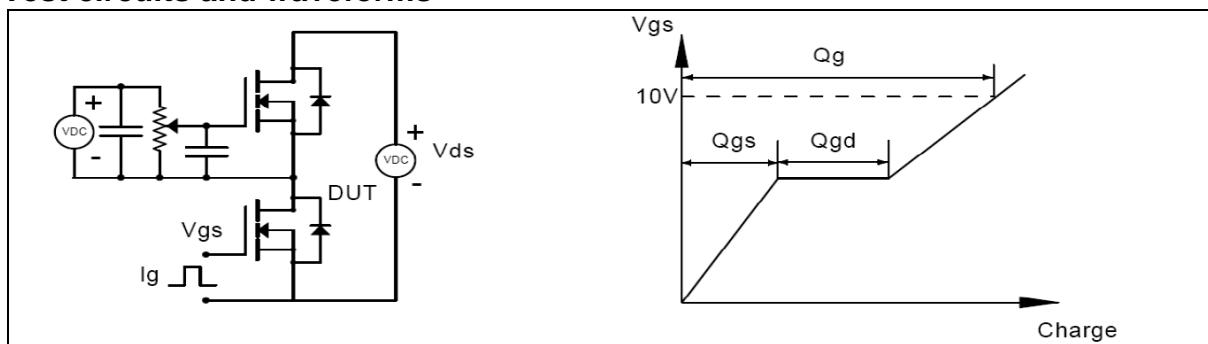
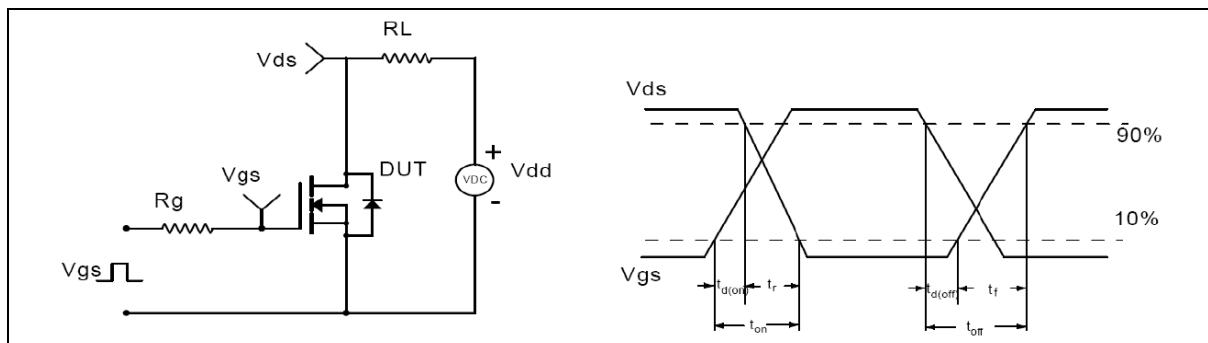
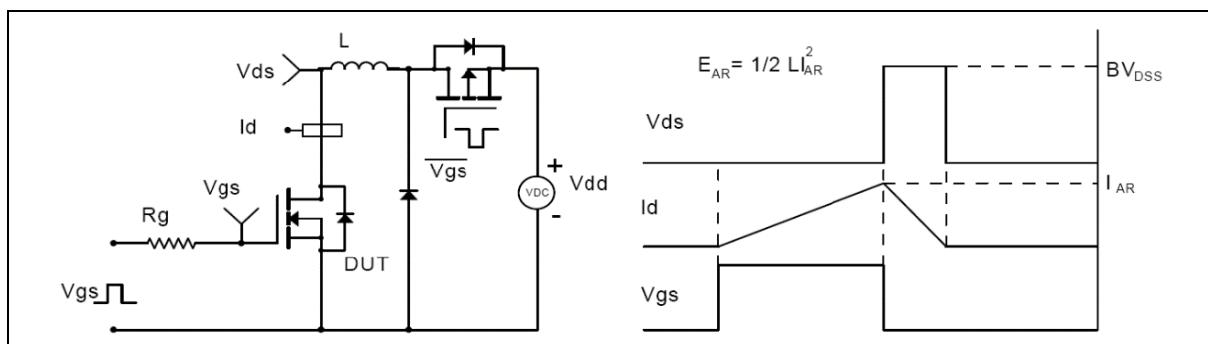
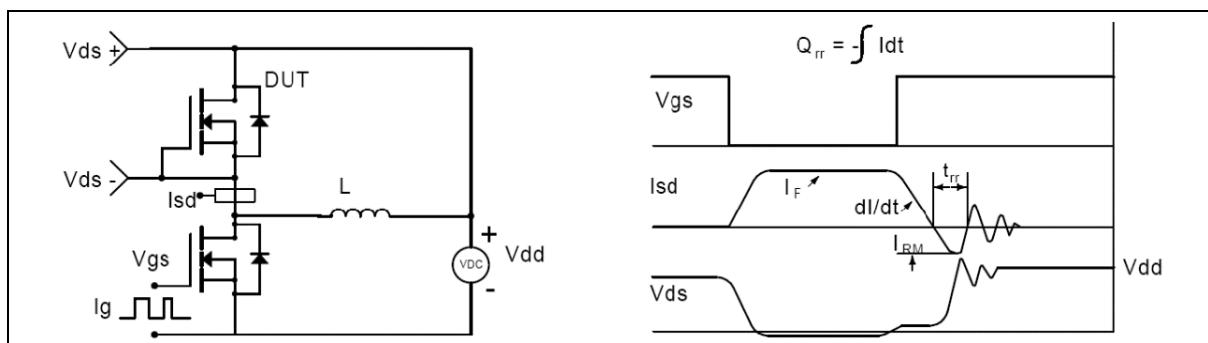
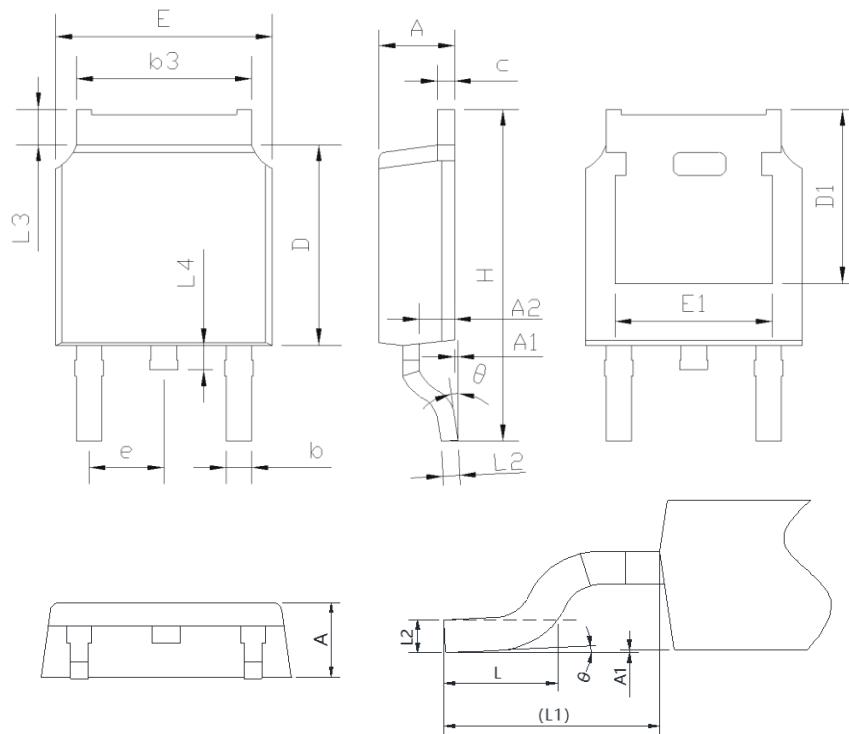


Figure 10. Safe operation area T_c=25 °C

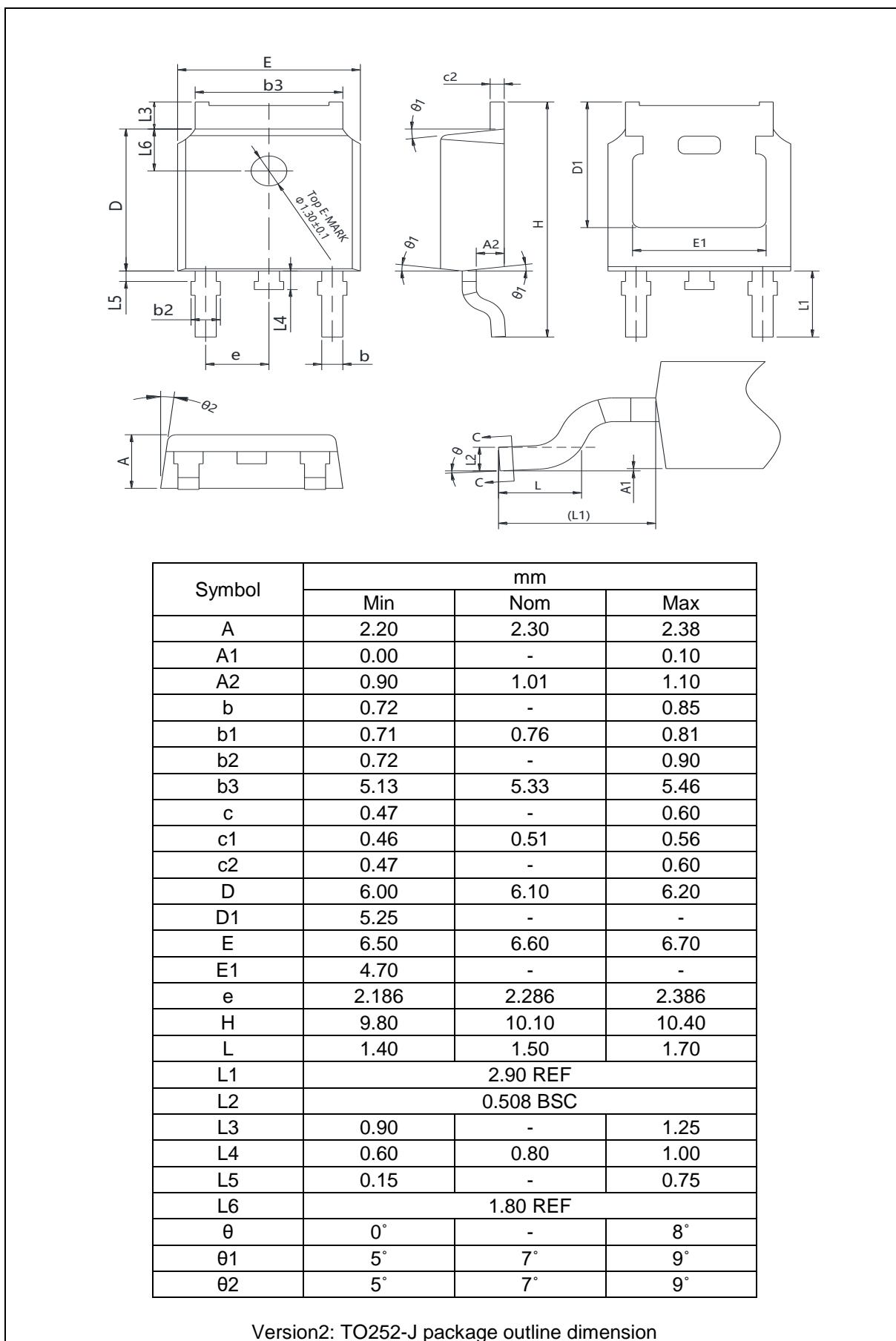
Test circuits and waveforms

Figure 1. Gate charge test circuit & waveform

Figure 2. Switching time test circuit & waveforms

Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms

Figure 4. Diode reverse recovery test circuit & waveforms

Package Information



Symbol	mm		
	Min	Nom	Max
A	2.20	2.30	2.38
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b3	5.20	5.33	5.46
c	0.43	0.53	0.61
D	5.98	6.10	6.22
D1	5.30 REF		
E	6.40	6.60	6.73
E1	4.63	-	-
e	2.286 BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90 REF		
L2	0.51 BSC		
L3	0.88	-	1.28
L4	0.50	-	1.00
θ	0°	-	8°

Version1: TO252-C package outline dimension



Ordering Information

Package Type	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Carton Box	Units/Carton Box
TO252-C	2500	2	5000	5	25000
TO252-J	2500	2	5000	5	25000

Product Information

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R670DF	TO252	yes	yes	yes

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